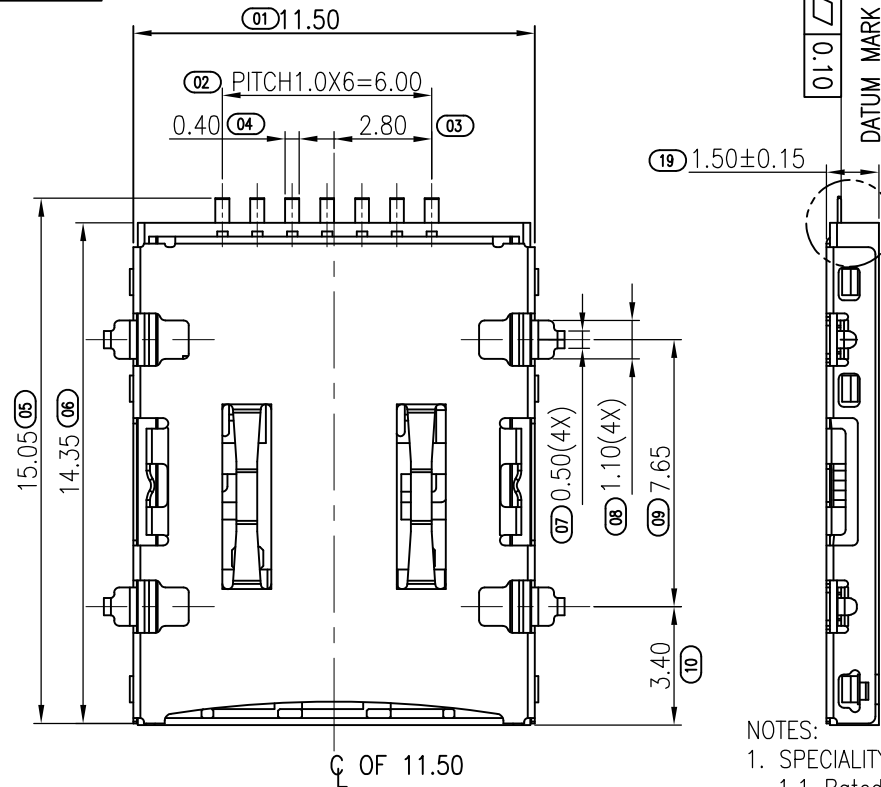


RoHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		新版发行	12/27'17	SUPER	SKY	WU

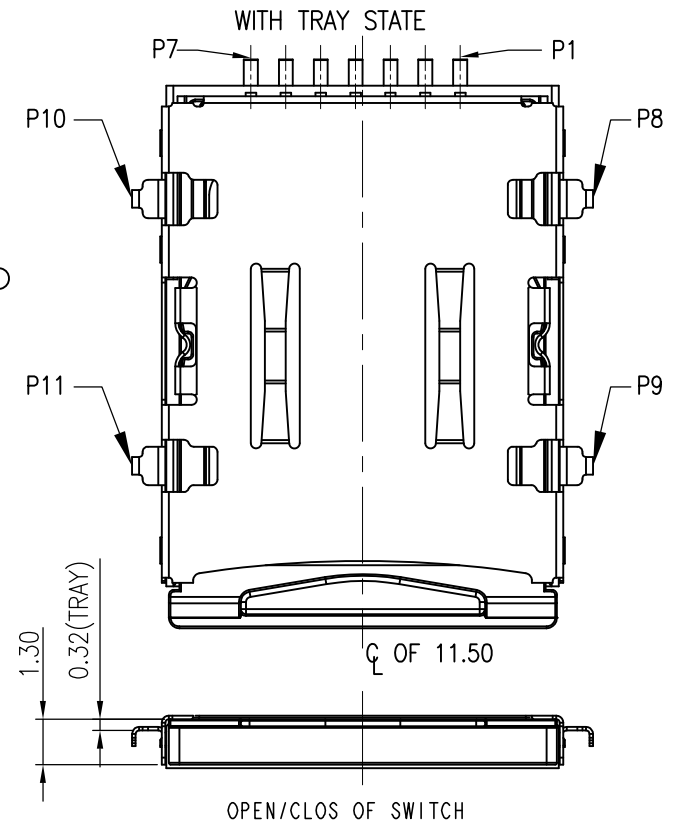


NOTES:

1. SPECIALITY:

- 1.1 Rated current:0.5A
- 1.2 Rated voltage:30V
- 1.3 Contact Resistance:50mΩ MAX
- 1.4 Insulation Resistance:1000MΩ MIN 500V DC
- 1.5 Dielectric withstanding voltage: 500V AC.
- 1.6 Solder ability:255±5℃, 5±0.5s.
- 1.7 Durability:3000 Cycles Min.
- 1.8 Operating condition:Temperature-40℃~+85℃;
Humidity 80% R.H MAX

2. PLEASE CONTACT JITS SALES REPRESENTATIVE TO
VERIFY PRODUCT DETAILS & AVAILABILITY



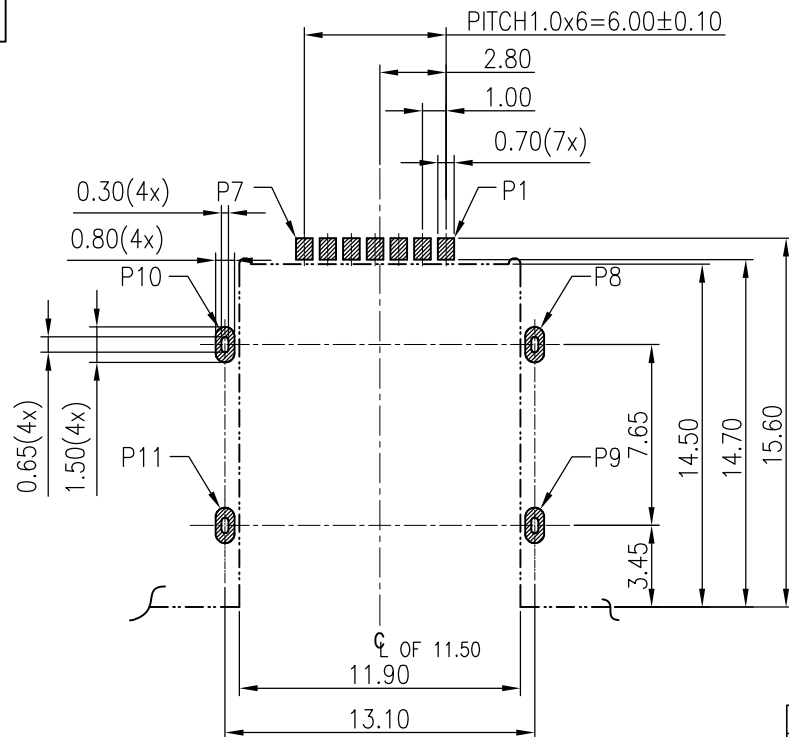
OPEN/CLOS OF SWITCH

DETECT SWITCH FOR CARD

CARD UNINSERTION	OPEN	P2	P1
CARD INSERTION	CLOSE	P2	P1
N/O		P2	P1

MILLIMETERS	INCH	UNITS MM	东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.			
X° ± 2°	X° ± 2°	MAT'L	PART NUMBER: XB-102011172		TITLE: NANO SIM H1.5沉板(带卡托)	
.X ± 0.30	.XX ± 0.012	SEE NOTES	APPD:		DWG NO.: C-102011172-00	
.XX ± 0.20	.XXX ± 0.008	FINISH	CHKD:		SCALE: 1:1SHEET: 1/3REV: A0	
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES	DR:			
		QTY				
		SEE NOTES				

RoHS



RECOMMENDED P.C. BOARD LAYOUT(MOUNT SURFACE)

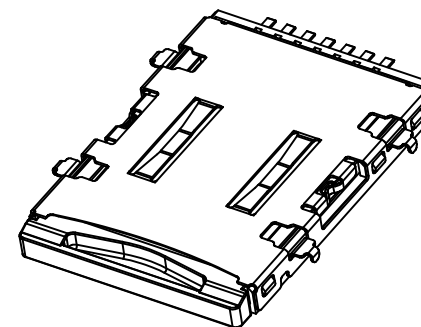
TOLERANCES UNLESS OTHERWISE SPEC.±0.05

NOTES:

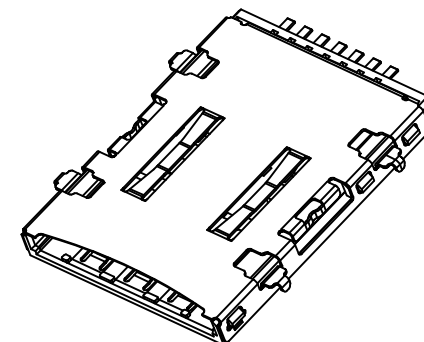
▨: PAD AREA

□: KEEP OUT AREA

CONNECTOR WITH TRAY

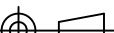


CONNECTOR

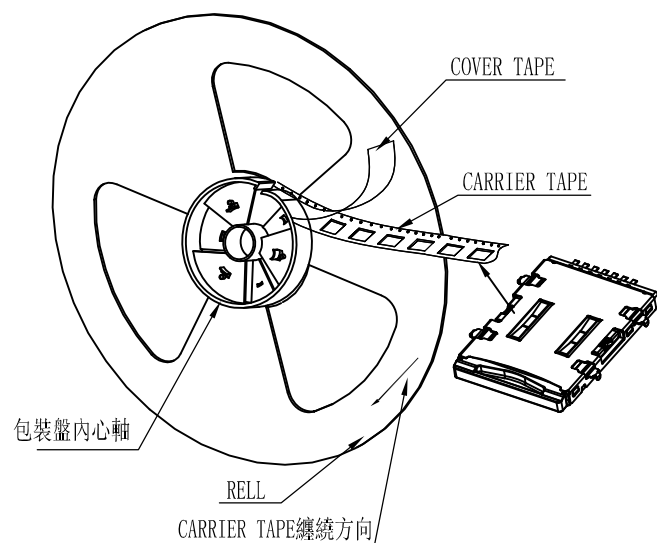


CONTACT PIN ASSIGNMENT		
PIN No.	No. FOR CARD	FUNCTION
P1	CD	CARD DETECT
P2	C5	GND
P3	C1	Vcc
P4	C6	Vpp
P5	C2	RST
P6	C7	I/O
P7	C3	CLK
P8	None	GND
P9	None	GND
P10	None	GND
P11	None	GND

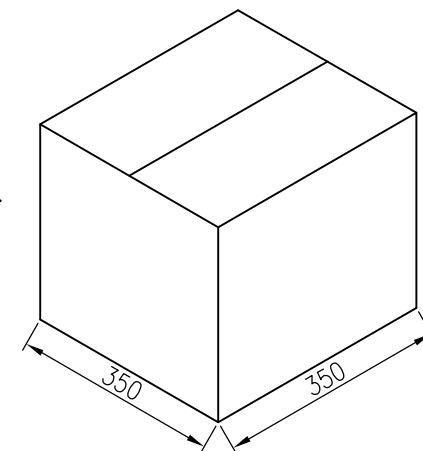
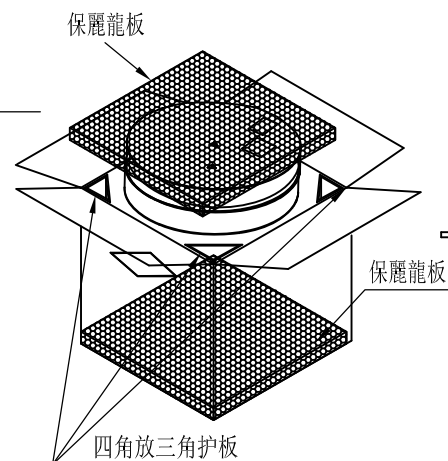
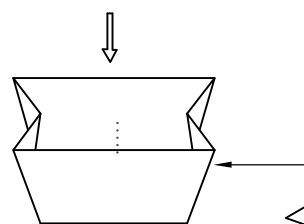
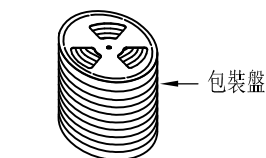
4	TRAY	1PCS	HIGH TEMPERATURE THERMOPLASTIC	UL94V-0;COLOR BLACK.
3	SHELL	1PCS	STAINLESS STEEL	NI PLATING
2	CONTACT	1PCS	COPPER ALLOY	NICKEL BASE, TERMINAL CONTACT POINT GOLD PLATED, SOLDER FEET FOG TIN
1	MOLDING	1PCS	HIGH TEMPERATURE THERMOPLASTIC	UL94V-0;COLOR BLACK.
NO	Description	Dosage	Material	Color/plating

MILLIMETERS	INCH	UNITS MM	东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.					
X° ± 2°	X° ± 2°	MAT'L						
.X ±0.30	.XX ±0.012	SEE NOTES	PART NUMBER:		TITLE:			
.XX ±0.20	.XXX ±0.008	FINISH	XB-102011172		NANO SIM HL.5沉板(带卡托)			
.XXX±0.10	.XXXX±0.004	SEE NOTES	APPD:		DWG NO.:			
		QTY	CHKD:		C-102011172-00			
		SEE NOTES	DR:			SCALE	SHEET	REV.
				1:1		2/3	A0	

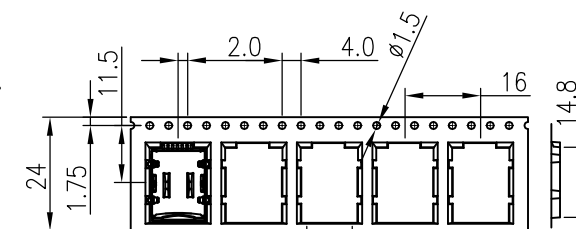
- 一、
- 1) 將成品一一放入包裝盤內, 依同一方向放入。
 - 2) 包裝時, 如圖所示。
 - 3) 一個包裝盤放置1500个成品。



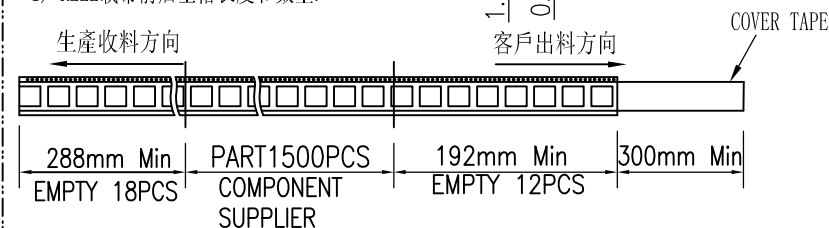
- 二、
- 1) 一只紙箱可放置10个包裝盤。
 - 2) 將10个包裝盤放在防水袋中。
 - 3) 箱底放保麗龍板, 再依次將指定数量的卷裝產品放入箱內, 四角分別放入四个三角护板, 最上层再放上保麗龍板。
 - 4) 一只紙箱可放15000PCS的成品。

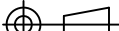


- 三、
- 1) RELL载帶尺寸图。



- 四、
- 1) RELL载帶前后空格长度和数量。



MILLIMETERS	INCH	UNITS MM	 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.			
X° ± 2°	X° ± 2°	MAT'L				
.X ± 0.30	.XX ± 0.012	SEE NOTES				
.XX ± 0.20	.XXX ± 0.008	FINISH				
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES				
			PART NUMBER: XB-102011172	TITLE: NANO SIM H1.5沉板(带卡托)		
			APPD:	DWG NO.: C-102011172-00		
			CHKD:			
			DR:			
			SCALE	SHEET	REV.	
			1:1	3/3	A0	